



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2020-08-13</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>giovanni giacopello</b>	<b>Representative Title</b>	<b>ADG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VND7030AJTR	STTI*XV13AES	A	64BA	2020-08-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	123	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00518989	



Package Designator	Size	Nbr of instances	Shape	
QFP	4.90,3.90,1.55	16	gull wing	
Comment	POWERSO-16			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.03	die	220
Lead	2.46	soft solder	19976

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.46	Soft solder	19976
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.457	Soft solder	925075

Material Composition Declaration :						Mfr Item Name	STTI*XV13AES					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	4.865	mg	supplier	die	Silicon(Si)	7440-21-3		4.538	mg	932785	36893
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.068	mg	13977	553
				supplier	metallisation	Copper(Cu)	7440-50-8		0.031	mg	6372	252
				supplier	metallisation	Gold(Au)	7440-57-5		0.007	mg	1439	57
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.027	mg	5550	220
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.013	mg	2672	106
				supplier	metallisation	Tungsten(W)	7440-33-7		0.107	mg	21994	870
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	411	16
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.011	mg	2261	89
				supplier	passivation	Silicon oxide	7631-86-9		0.061	mg	12539	496
Leadframe	M-004 Copper and its alloys	69.407	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		67.569	mg	973518	549341
				supplier	alloy & coating	Iron(Fe)	7439-89-6		1.589	mg	22894	12919
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.096	mg	1383	780
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.083	mg	1196	675
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.070	mg	1009	569
Soft solder	Solder	2.656	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	2.457	mg	925076	19976
				supplier	solder	Tin(Sn)	7440-31-5		0.133	mg	50075	1081
				supplier	solder	Silver(Ag)	7440-22-4		0.066	mg	24849	537
Bonding wires	M-004 Copper and its alloys	0.496	mg	supplier	wire	Copper(Cu)	7440-50-8		0.496	mg	1000000	4033
Bonding wires 2	M-004 Copper and its alloys	0.341	mg	supplier	wire	Copper(Cu)	7440-50-8		0.341	mg	1000000	2772
Encapsulation	M-011 Other inorganic materials	43.939	mg	supplier	mold compound	Silica vitreous	60676-86-0		37.963	mg	863994	308642
				supplier	mold compound	Epoxy type resin	proprietary		3.295	mg	74990	26789
				supplier	mold compound	Phenol type resin	proprietary		2.197	mg	50001	17862
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		0.220	mg	5007	1789
				supplier	mold compound	Quartz	14808-60-7		0.132	mg	3004	1073
				supplier	mold compound	Carbon black	1333-86-4		0.132	mg	3004	1073
connections coating	Solder	1.296	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.296	mg	1000000	10537